

TRAY FLATTENER**Abstract**

Semiconductor devices are typically manufactured from strips. The semiconductor
5 devices are then separated from the strips into individual units. The individual units are
washed, dried and placed into rows of component pockets located on JEDEC matrix
trays (trays). However, tray warping tends to occur at the centre of the trays due to
improper securing of the trays thereby resulting in misaligned component pockets.
Hence, the individual units are not accurately positioned and secured into the component
10 pockets. Additionally, the size of the individual units further worsens the problem of
tray-warping as the individual units are easily displaceable from the component pockets
when not properly secured in the component pockets. An embodiment of the invention
describes an apparatus and a method for un-warping trays used for containing
semiconductor devices.

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FIG. 6